

Encapsulants

Product Name	Description	Key Attributes	Viscosity at 25°C (cP)	Glass Transition Temperature, T _g (°C)	Coefficient of Thermal Expansion, CTE (ppm/°C)		Modulus at 25°C (MPa)	Recommended Cure
					Below T _g	Above T _g		
Dam								
LOCTITE ECCOBOND FP4451TD	Epoxy dam encapsulant	<ul style="list-style-type: none"> • Excellent chemical resistance and thermal stability • High thixotropy with high height-to-width aspect ratio (0.7) • Designed for use with fill encapsulant LOCTITE ECCOBOND FP4450 	300,000	150	21	65	14,300	30 min. at 125°C + 90 min. at 165°C
Fill								
LOCTITE ECCOBOND FP4450	Epoxy fill encapsulant	<ul style="list-style-type: none"> • Low stress • Good moisture resistance and excellent chemical resistance • Exhibits relatively high flow • Excellent pressure pot performance on live devices up to 500 hr. 	43,900	155	22	80	13,500	30 min. at 125°C + 90 min. at 165°C
Glob Top								
LOCTITE ECCOBOND E01072	Epoxy glob top encapsulant	<ul style="list-style-type: none"> • High T_g • Low extractable ionics • High performance • Long shelf life • Fast curing • One component 	80,000	135	43	123	6,700	5 min. at 140°C – 150°C